

# SSN1N45B

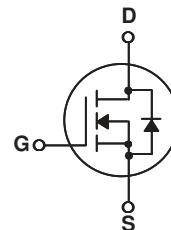
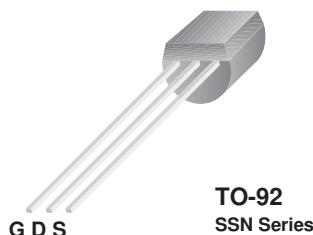
## 450V N-Channel MOSFET

### General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for electronic ballasts based on half bridge configuration.

### Features

- 0.5A, 450V,  $R_{DS(on)} = 4.25\Omega$  @  $V_{GS} = 10$  V
- Low gate charge ( typical 6.5 nC)
- Low  $C_{rss}$  ( typical 6.5 pF)
- 100% avalanche tested
- Improved dv/dt capability
- Gate-Source Voltage  $\pm 50$ V guaranteed



### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	SSN1N45B	Units
$V_{DSS}$	Drain-Source Voltage	450	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	0.5	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	0.32	A
$I_{DM}$	Drain Current - Pulsed	(Note 1)	A
$V_{GSS}$	Gate-Source Voltage	$\pm 50$	V
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	mJ
$I_{AR}$	Avalanche Current	(Note 1)	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	V/ns
$P_D$	Power Dissipation ( $T_A = 25^\circ\text{C}$ )	0.9	W
	Power Dissipation ( $T_L = 25^\circ\text{C}$ )	2.5	W
	- Derate above $25^\circ\text{C}$	0.02	W/ $^\circ\text{C}$
$T_J, T_{stg}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JL}$	Thermal Resistance, Junction-to-Lead	(Note 6a)	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 6b)	--	$^\circ\text{C}/\text{W}$

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	450	--	--	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.5	--	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 450 \text{ V}$ , $V_{\text{GS}} = 0 \text{ V}$	--	--	10	$\mu\text{A}$
		$V_{\text{DS}} = 360 \text{ V}$ , $T_C = 125^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{\text{GSSF}}$	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 50 \text{ V}$ , $V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA
$I_{\text{GSSR}}$	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -50 \text{ V}$ , $V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA

## On Characteristics

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250 \mu\text{A}$	2.3	3.0	3.7	V
		$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250 \text{ mA}$	3.5	4.2	4.9	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}$ , $I_D = 0.25 \text{ A}$	--	3.4	4.25	$\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}} = 50 \text{ V}$ , $I_D = 0.25 \text{ A}$	--	0.7	--	S

## Dynamic Characteristics

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$ , $V_{\text{GS}} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	--	185	240	pF
$C_{\text{oss}}$	Output Capacitance		--	29	40	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	6.5	8.5	pF

## Switching Characteristics

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 225 \text{ V}$ , $I_D = 0.5 \text{ A}$ , $R_G = 25 \Omega$	--	7.5	25	ns
$t_r$	Turn-On Rise Time		--	21	50	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	23	55	ns
$t_f$	Turn-Off Fall Time		--	36	80	ns
$Q_g$	Total Gate Charge	$V_{\text{DS}} = 360 \text{ V}$ , $I_D = 0.5 \text{ A}$ , $V_{\text{GS}} = 10 \text{ V}$	--	6.5	8.5	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	0.9	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	3.2	--	nC

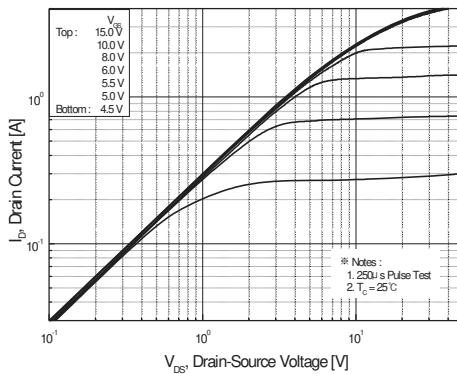
## Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	0.5	A	
$I_{\text{SM}}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	4.0	A	
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$ , $I_S = 0.5 \text{ A}$	--	--	1.4	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}$ , $I_S = 0.5 \text{ A}$ ,	--	102	--	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI_F / dt = 100 \text{ A}/\mu\text{s}$	(Note 4)	--	0.26	$\mu\text{C}$

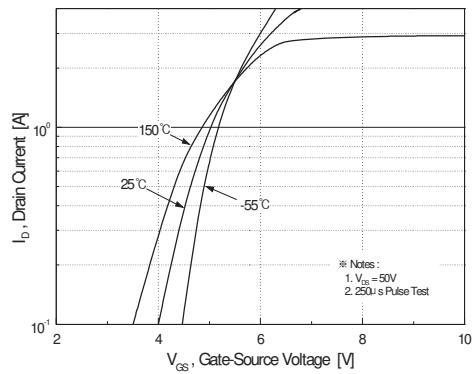
### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 75\text{mH}$ ,  $I_{AS} = 1.6\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25 \Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 0.5\text{A}$ ,  $dI/dt \leq 300\text{A}/\mu\text{s}$ ,  $V_{DD} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature
6. a) Reference point of the  $R_{\theta JL}$  is the drain lead  
b) When mounted on 3"x4.5" FR-4 PCB without any pad copper in a still air environment  
( $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance.  $R_{\theta CA}$  is determined by the user's board design)

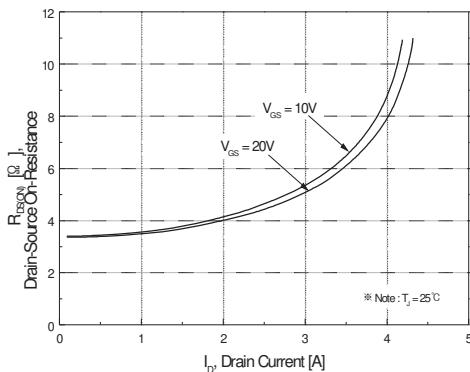
## Typical Characteristics



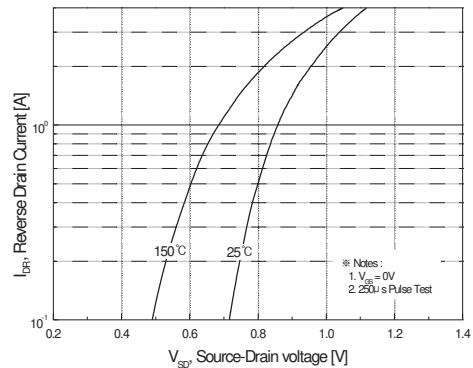
**Figure 1. On-Region Characteristics**



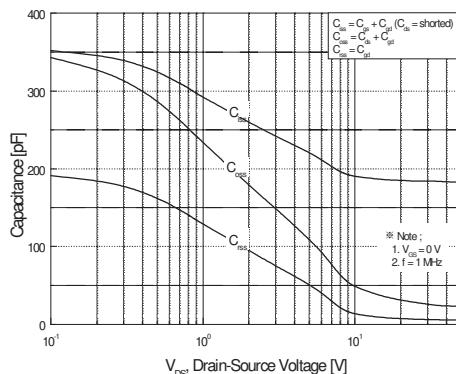
**Figure 2. Transfer Characteristics**



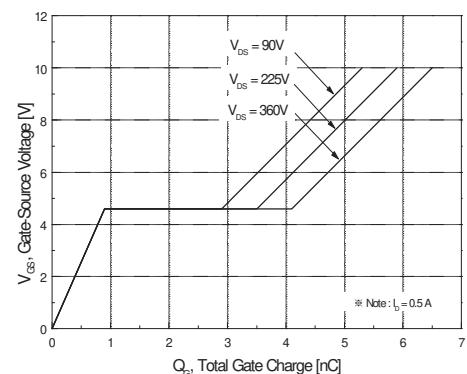
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

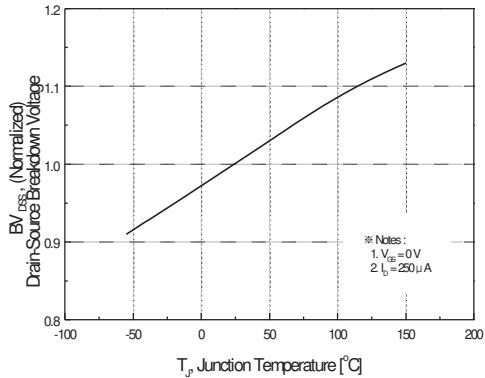


**Figure 5. Capacitance Characteristics**

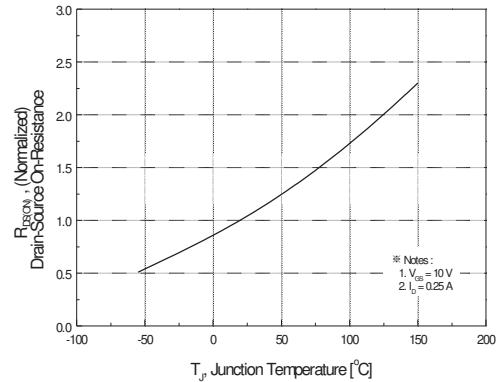


**Figure 6. Gate Charge Characteristics**

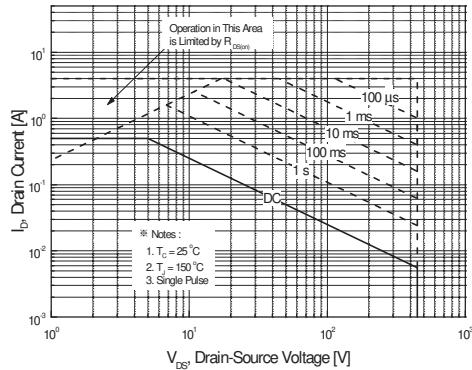
## Typical Characteristics (Continued)



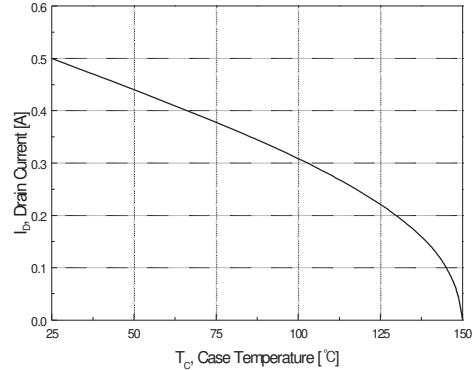
**Figure 7. Breakdown Voltage Variation vs. Temperature**



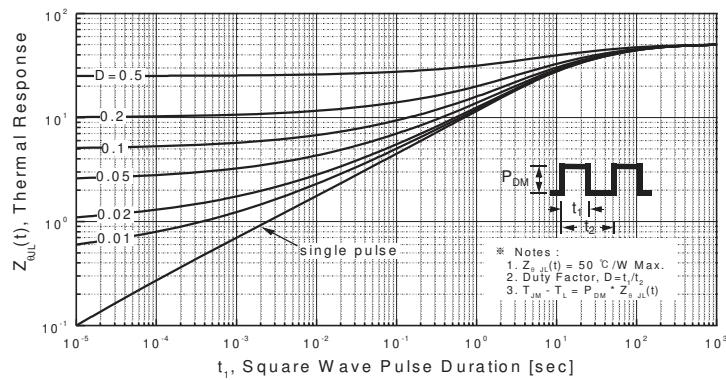
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**

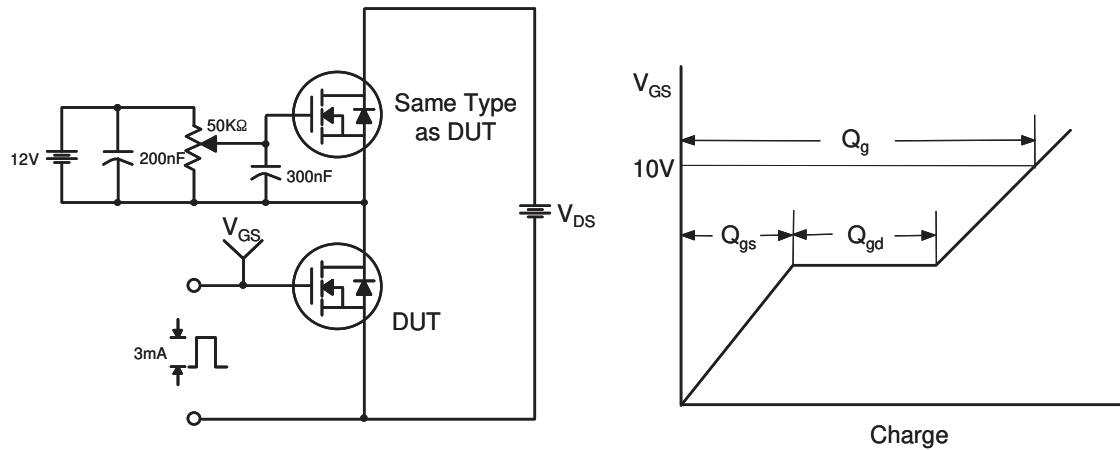


**Figure 10. Maximum Drain Current vs. Case Temperature**

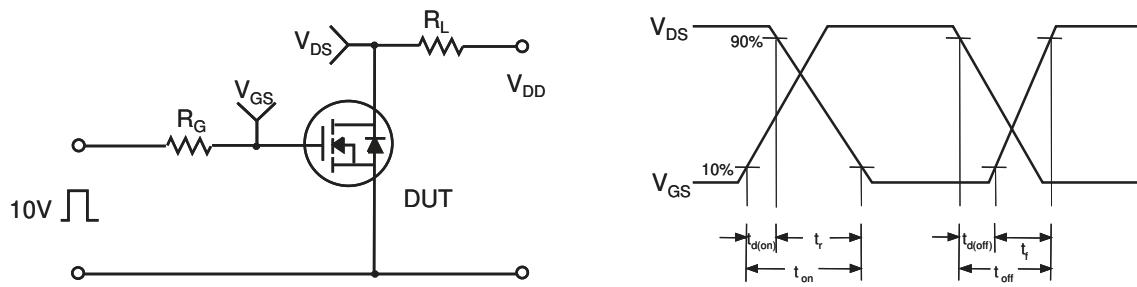


**Figure 11. Transient Thermal Response Curve**

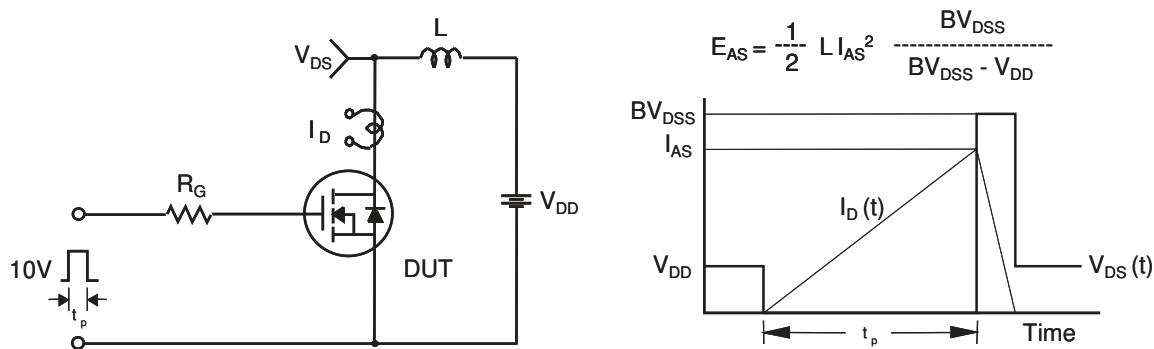
## Gate Charge Test Circuit &amp; Waveform



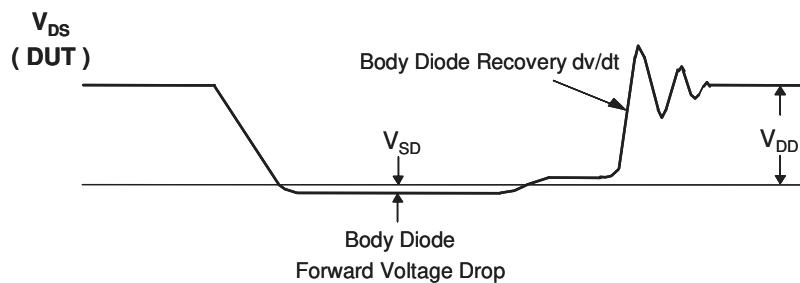
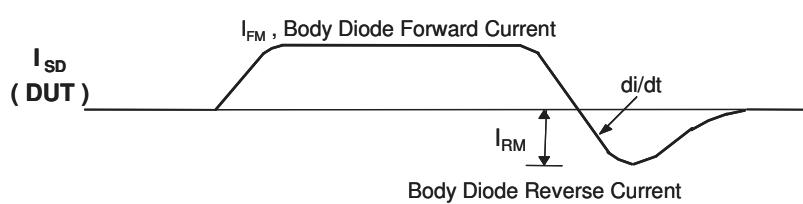
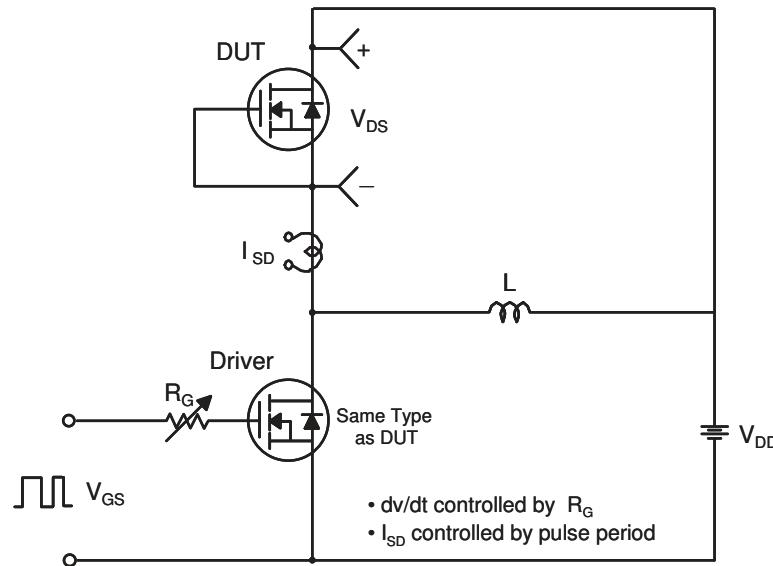
## Resistive Switching Test Circuit &amp; Waveforms



## Unclamped Inductive Switching Test Circuit &amp; Waveforms



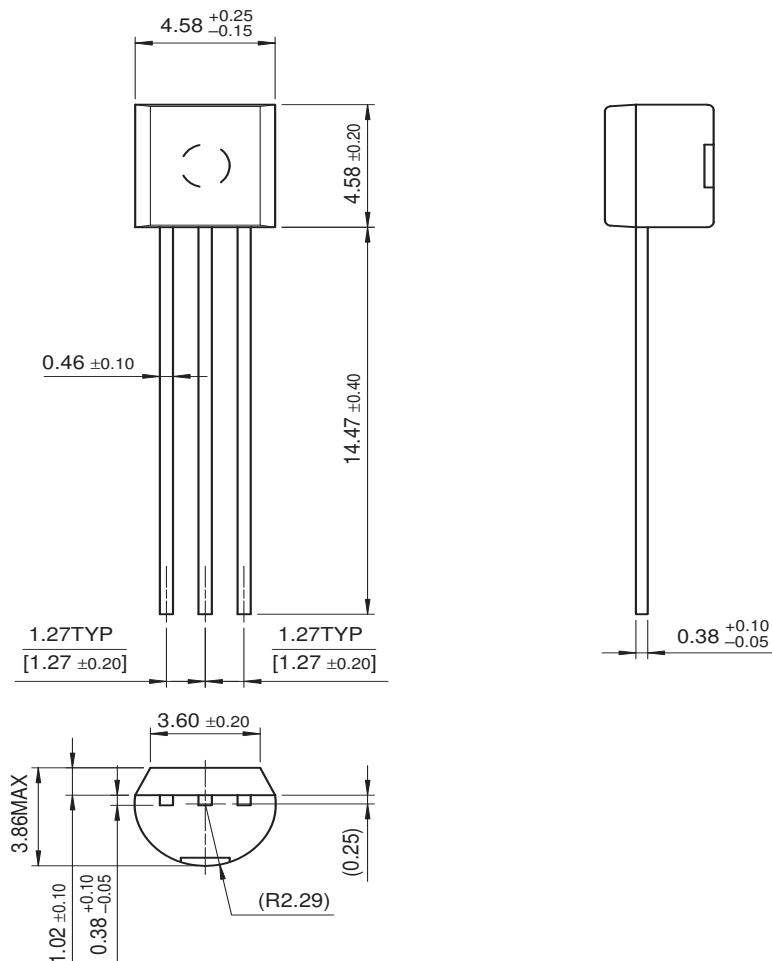
## Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms



SSN1N45B

## Package Dimensions

TO-92



Dimensions in Millimeters

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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450V N-Channel B-FET

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### General description

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- Gate-Source Voltage  $\pm 50\text{V}$  guaranteed

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### Product status/pricing/packaging

**BUY**

Product	Product status	Pb-free Status	Pricing*	Package type	Leads	Packing method	Package Marking Convention**

 SSN1N45BBU	Full Production	 Full Production	\$0.466	TO-92	3	BULK	<a href="#">Line 1: 1N45B Line 2: 3</a>
 SSN1N45BTA	Full Production	 Full Production	\$0.394	TO-92	3	AMMO	<a href="#">Line 1: 1N45B Line 2: 3</a>

\* Fairchild 1,000 piece Budgetary Pricing

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